ON Semiconductor 10/15/2019				
Base Part		FAN3214T	HF	Pb-free
Orderable Part		FAN3214TMX	Total weight (mg)	80.792
Homogenous Material	Weight (mg)	Substance in Mat.	CAS#	% Avg. Weight
Die	2.16	Silicon (Si)	7440-21-3	100
Die Attach		Silver (Ag)	7440-22-4	74
	1.144	Phenolic Resin-2	54208-63-8	26
Lead Frame		Zinc (Zn)	7440-66-6	0.12525694
		Iron (Fe)	7439-89-6	2.35097636
		Copper (Cu)	7440-50-8	97.44026208
	31.136	Phosphorus (P)	7723-14-0	0.08350462
Mold Compound- Black		Ortho Cresol Novolac Resin	29690-82-2	6.24862
		Carbon Black (C)	1333-86-4	0.19871936
		Silica (SiO2)	14464-46-1	87.03908147
	45.29	Phenolic Resin (Novolac)	9003-35-4	6.51357916
Plating		Silver (Ag)	7440-22-4	1.6091954
		Palladium (Pd)	7440-05-3	3.44827586
		Nickel (Ni)	7440-02-0	92.87356322
	0.435	Gold (Au)	7440-57-5	2.06896552
Wire Bond - Au	0.627	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF